2013311-1 ✕ OBSOLETE

RAYCHEM RVS
TE Internal #: 2013311-1

TE Internal Description: SEMI-HARD TRAY DDR3 204P 9.2H RVS

View on TE.com >

Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets

DRAM Type: **Double Data Rate (DDR) 3**

Stack Height: **9.2 mm [.362 in]**

Module Orientation: **Right Angle**

Number of Positions: **204**

Centerline (Pitch): **.6 mm [.024 in]**

Features

Product Type Features

DRAM Type	Double Data Rate (DDR) 3
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	204

Electrical Characteristics

DRAM Voltage	1.5 V

Signal Characteristics

SGRAM Voltage	1.5 V

Body Features

Ejector Location	Both Ends
Latch Material	Stainless Steel
Latch Plating Material	Tin
Module Key Type	SGRAM
Ejector Type	Locking

Contact Features

Memory Socket Type	Memory Card
PCB Contact Termination Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash

Termination Features

Insertion Style	Cam-In

Mechanical Attachment

Mating Alignment Type	Reverse Keying
PCB Mounting Style	Surface Mount
PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.6 mm[.024 in]

Dimensions

Stack Height	9.2 mm[.362 in]
Row-to-Row Spacing	8.2 mm[.322 in]

Industry Standards

UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	20
Packaging Method	Semi-Hard Tray Assembly

Other

Socket Connector Comment	With floating peg.

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	

Current ECHA Candidate List: JUNE 2022
(224)
Candidate List Declared Against: JUN 2018
(191)
Does not contain REACH SVHC

Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Also in the Series | RAYCHEM RVS

Joints & Splices(4)

RJ45 Connectors(1)

SD Card Connectors(2)

SO DIMM Sockets(13)

Documents

CAD Files
Customer View Model
ENG_CVM_CVM_2013311-1_C.2d_dxf.zip

English

3D PDF

3D

Customer View Model
ENG_CVM_CVM_2013311-1_C.3d_igs.zip

English

Customer View Model
ENG_CVM_CVM_2013311-1_C.3d_stp.zip

English

Product Specifications

Product Specification

English